

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6940611

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HSIN-HUNG CHOU	09/10/2021
TSUNG-WEI LIN	09/10/2021
KAO-TSAIR TSAI	09/10/2021
RECEIVING PARTY DATA	
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City:	TAICHUNG CITY
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17480757
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NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe McKinney Muncy/
DATE SIGNED:	09/28/2021
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, Hsin-Hung CHOU, Tsung-Wei LIN and Kao-Tsair TSAI hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR FORMING SEMICONDUCTOR MEMORY STRUCTURE

Filed: 21 Sep 2021

Serial No. 17/480,757

Executed on: _____

WHEREAS, Winbond Electronics Corp. of No. 8 Keya 1st Rd., Daya District, Central Taiwan Science Park, Taichung City, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Hsin-Hung CHOU
Hsin-Hung CHOU

September 10, 2021
Date

Tsung-Wei Lin
Tsung-Wei LIN

September 10, 2021
Date

Kao-Tsair TSAI
Kao-Tsair TSAI

September 10, 2021
Date